

FIG. 1

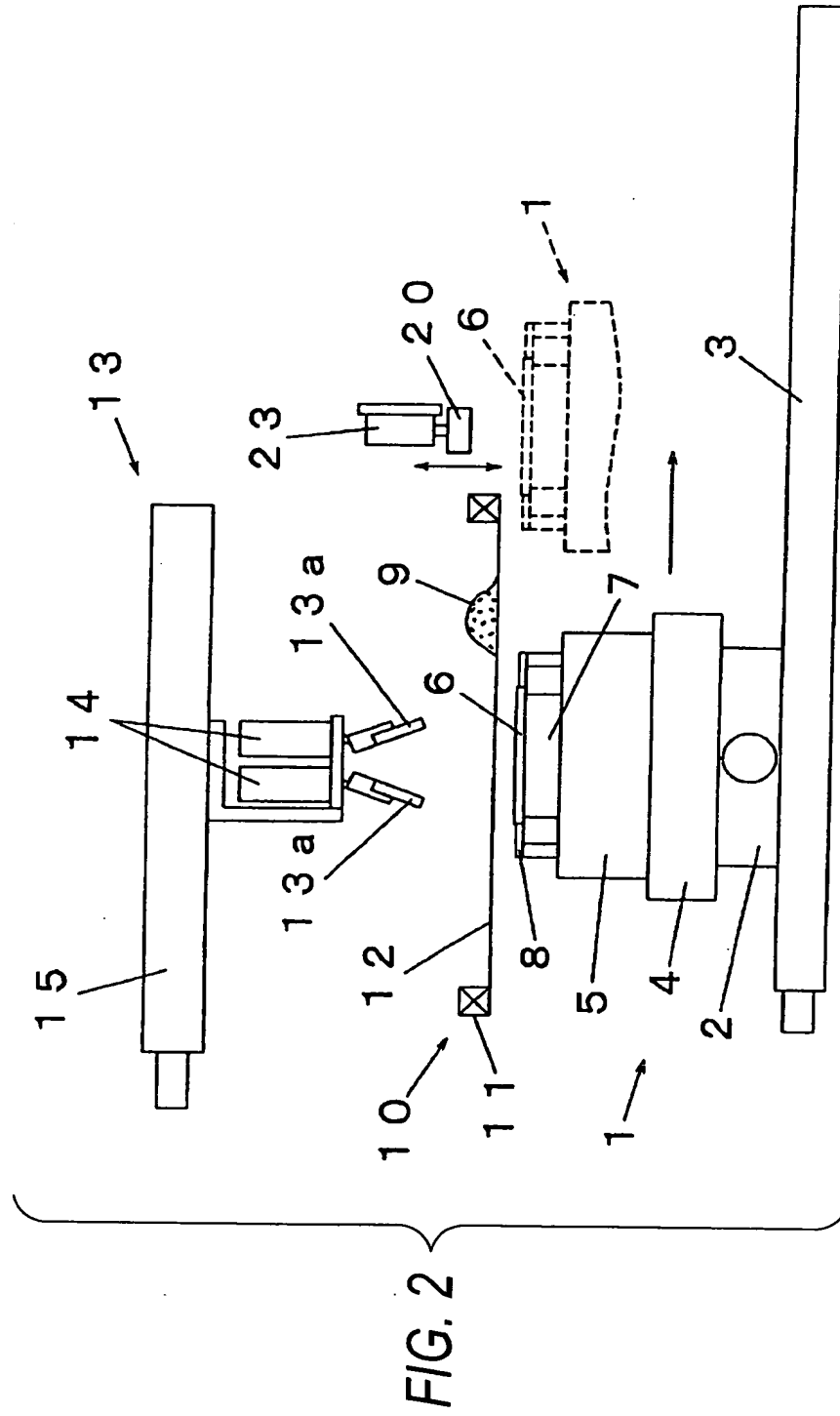


FIG. 3

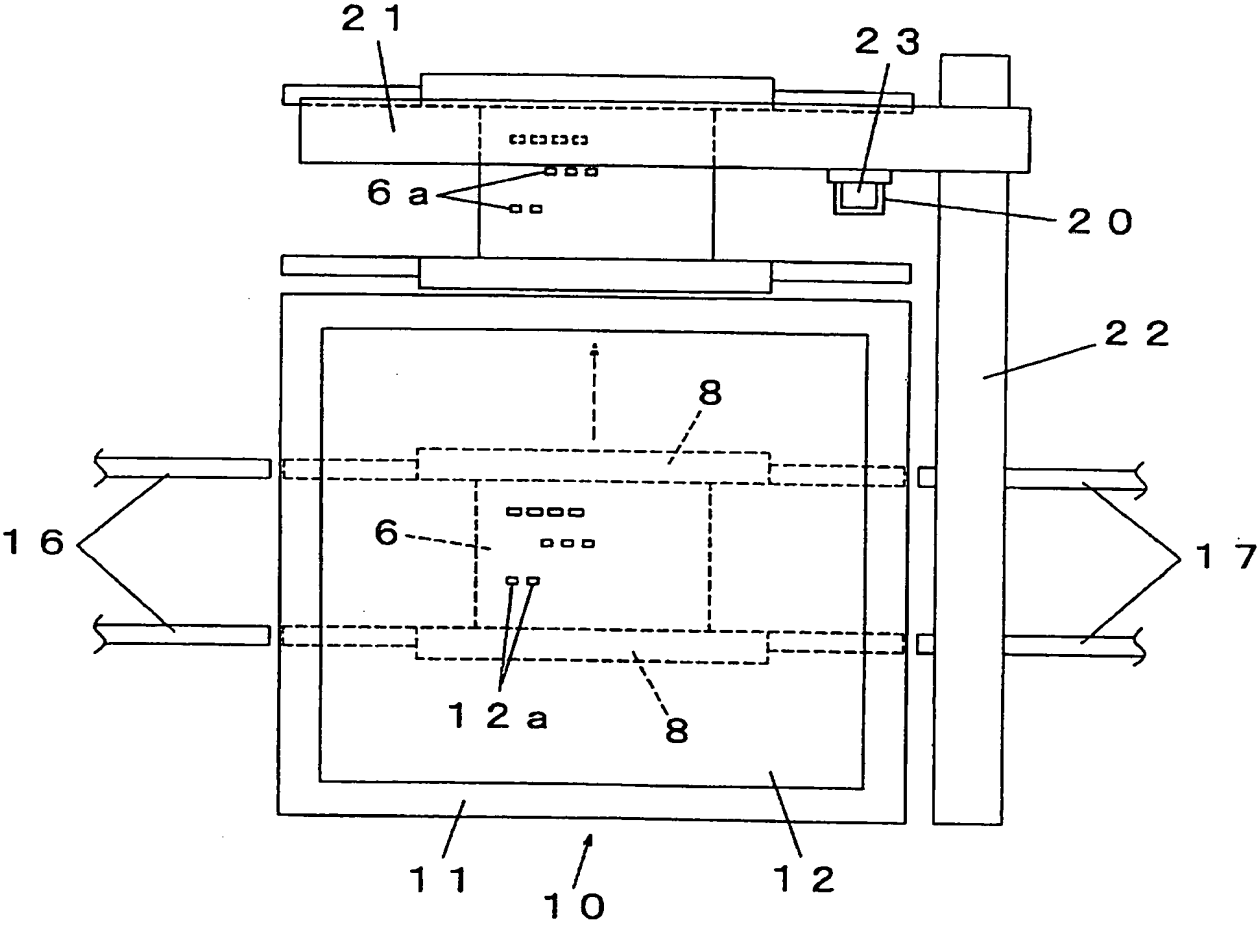


FIG. 4

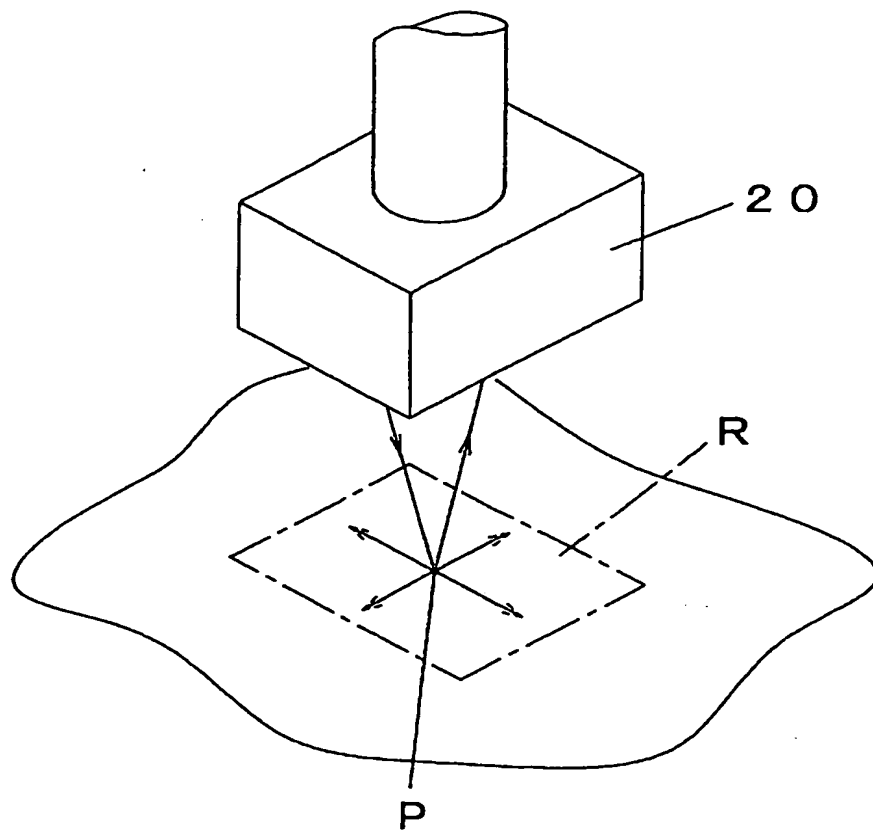


FIG. 5

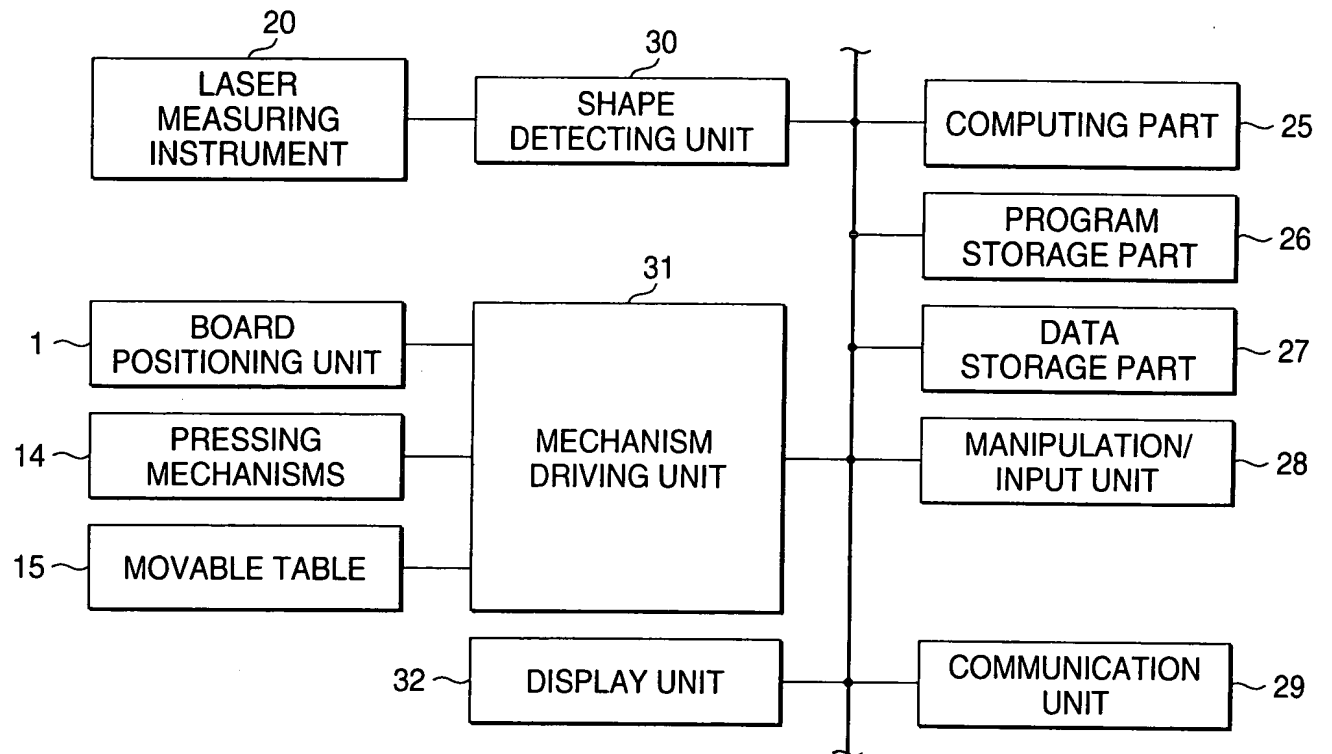


FIG. 6

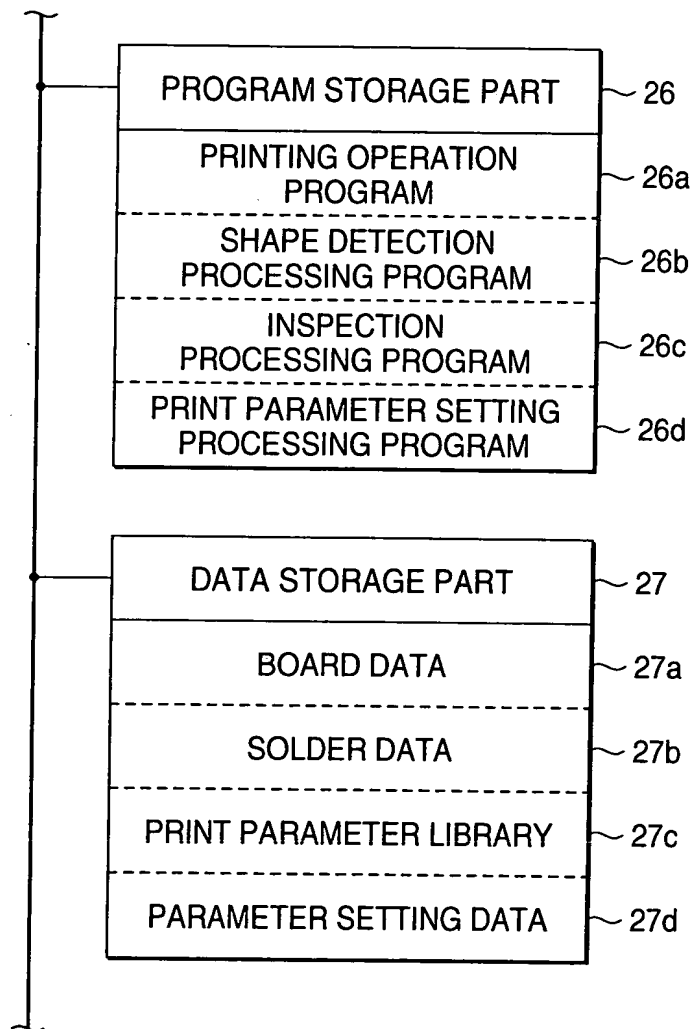


FIG. 7

PATTERN NAME	A	B	C	
PARAMETER	S1	S2	S3	
SQUEEGEE MOVEMENT SPEED	V1	V2	V3	
PRINTING PRESSURE	P1	P2	P3	
PLATE RELEASE PATTERN	I	II	III	
PLATE RELEASE SPEED	v1	v2	v3	

FIG. 8

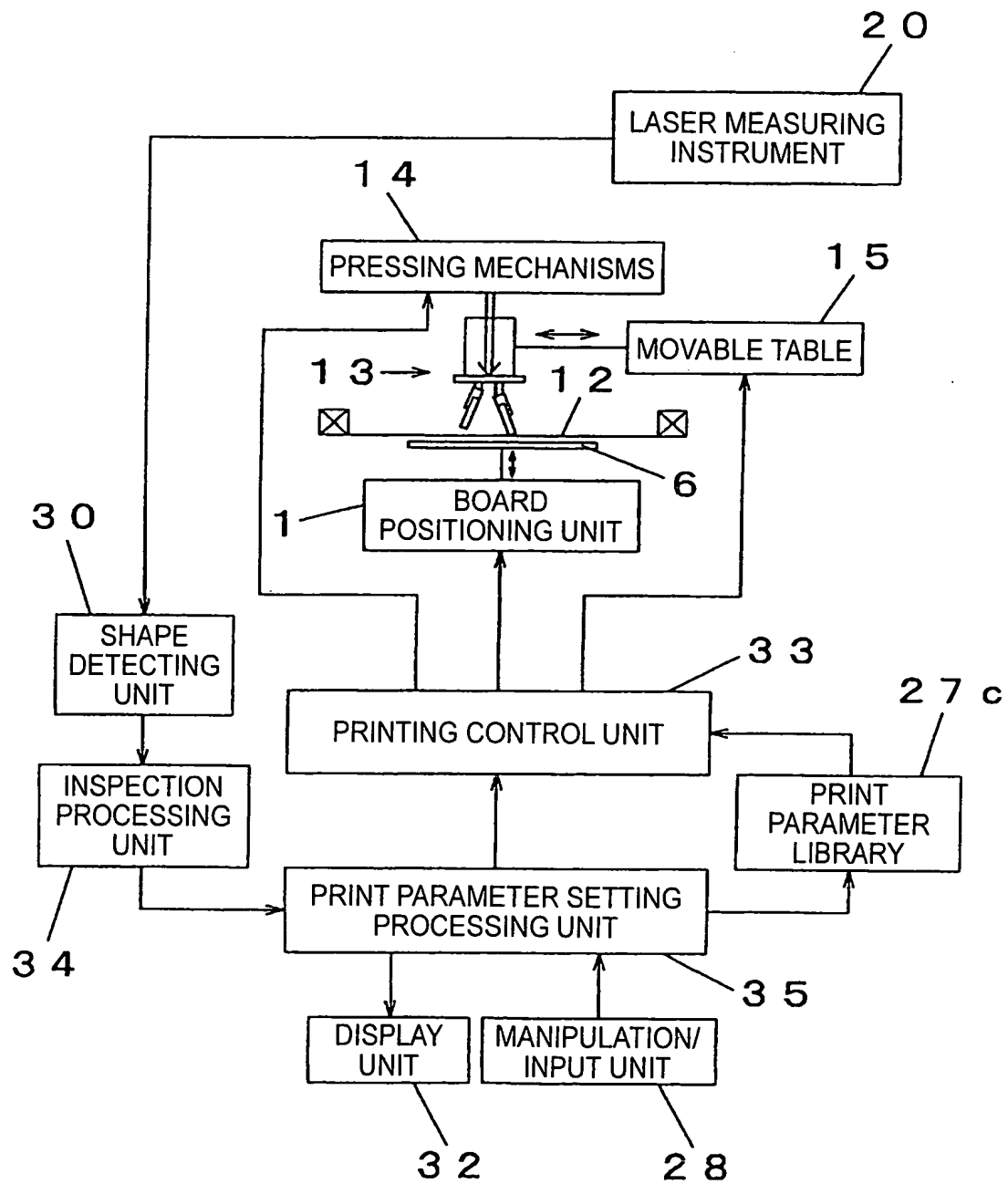


FIG. 9

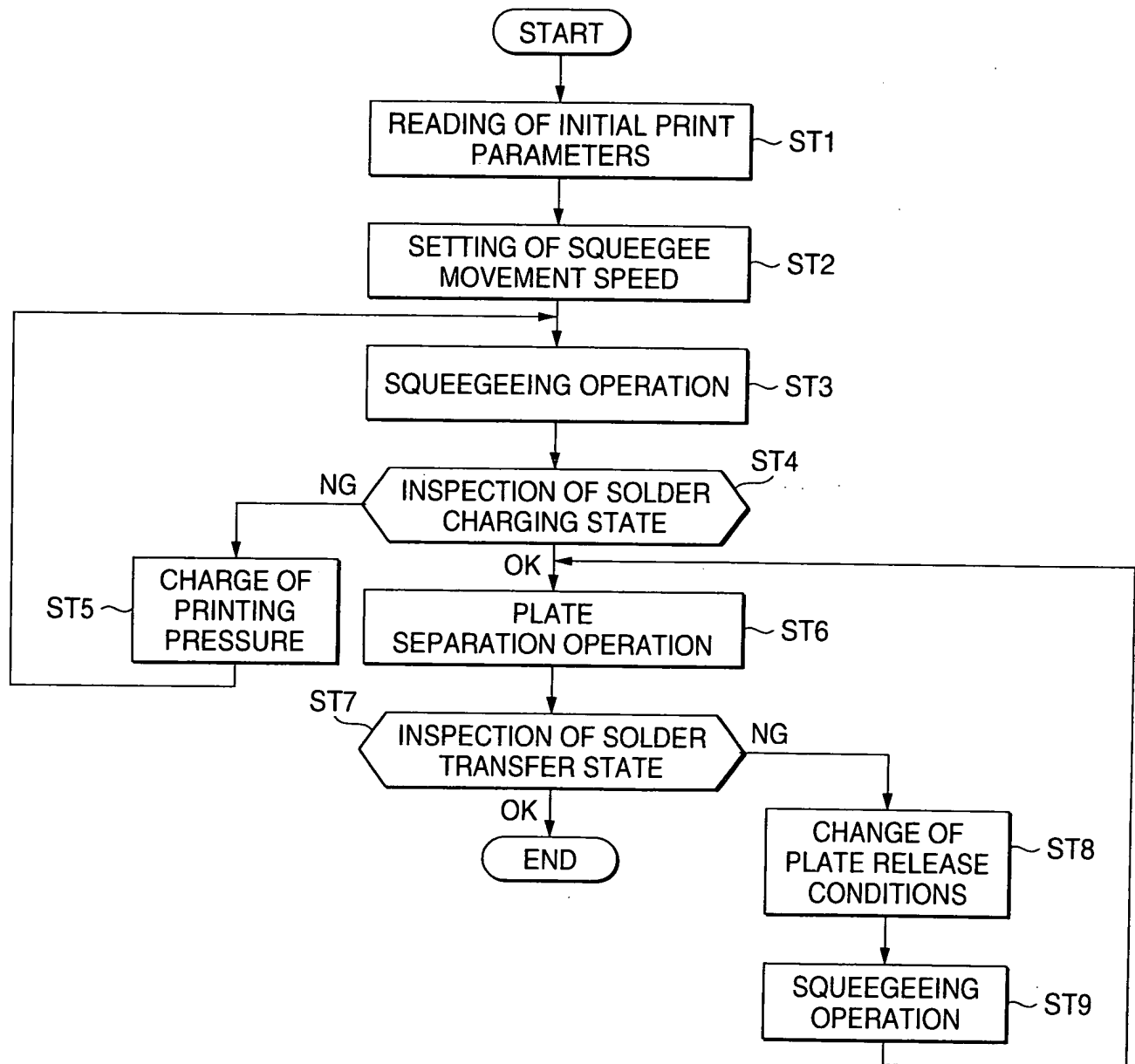


FIG. 10 (a)

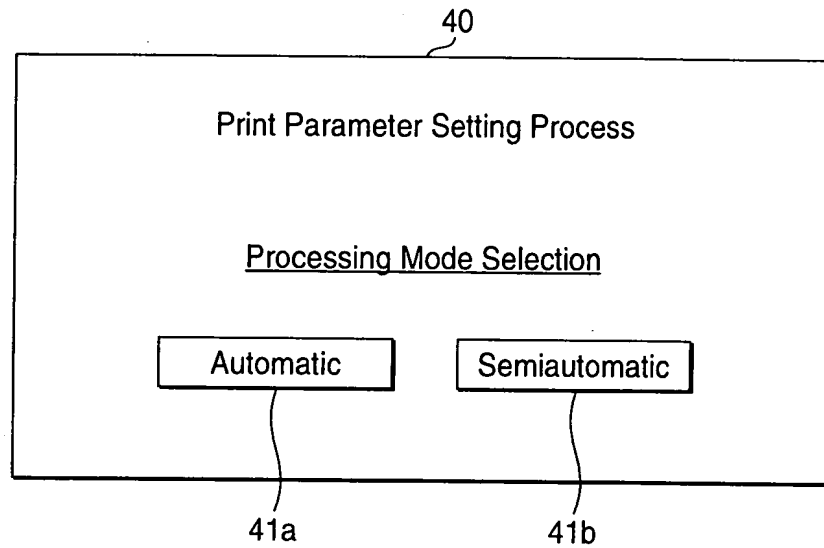


FIG. 10 (b)

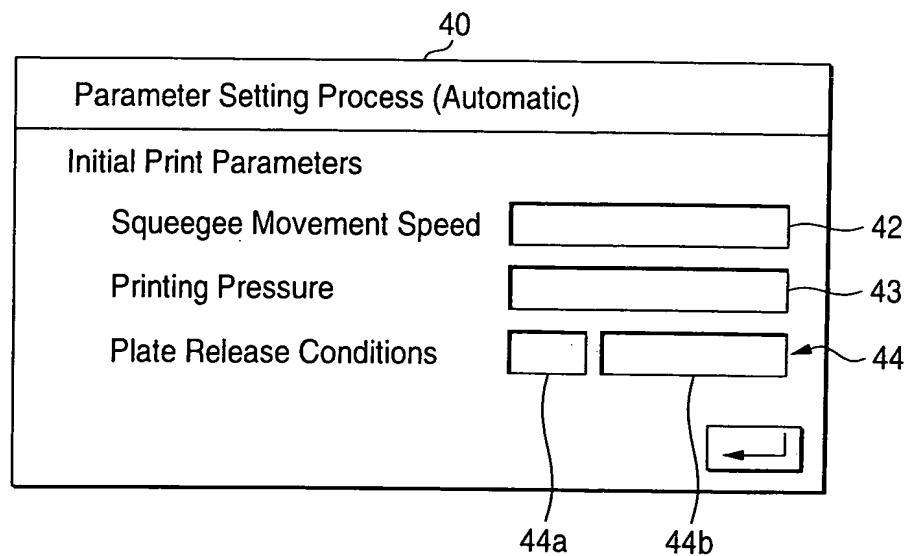


FIG. 11 (a)

40

Parameter Setting Process (Automatic)

Parameter Confirmation

Squeegee Movement Speed 42

Printing Pressure 43

Plate Release Conditions 44

45a 45b

FIG. 11 (b)

40

Parameter Setting Process (Automatic)

Parameter Name 46

Solder Type 47

48

FIG. 12

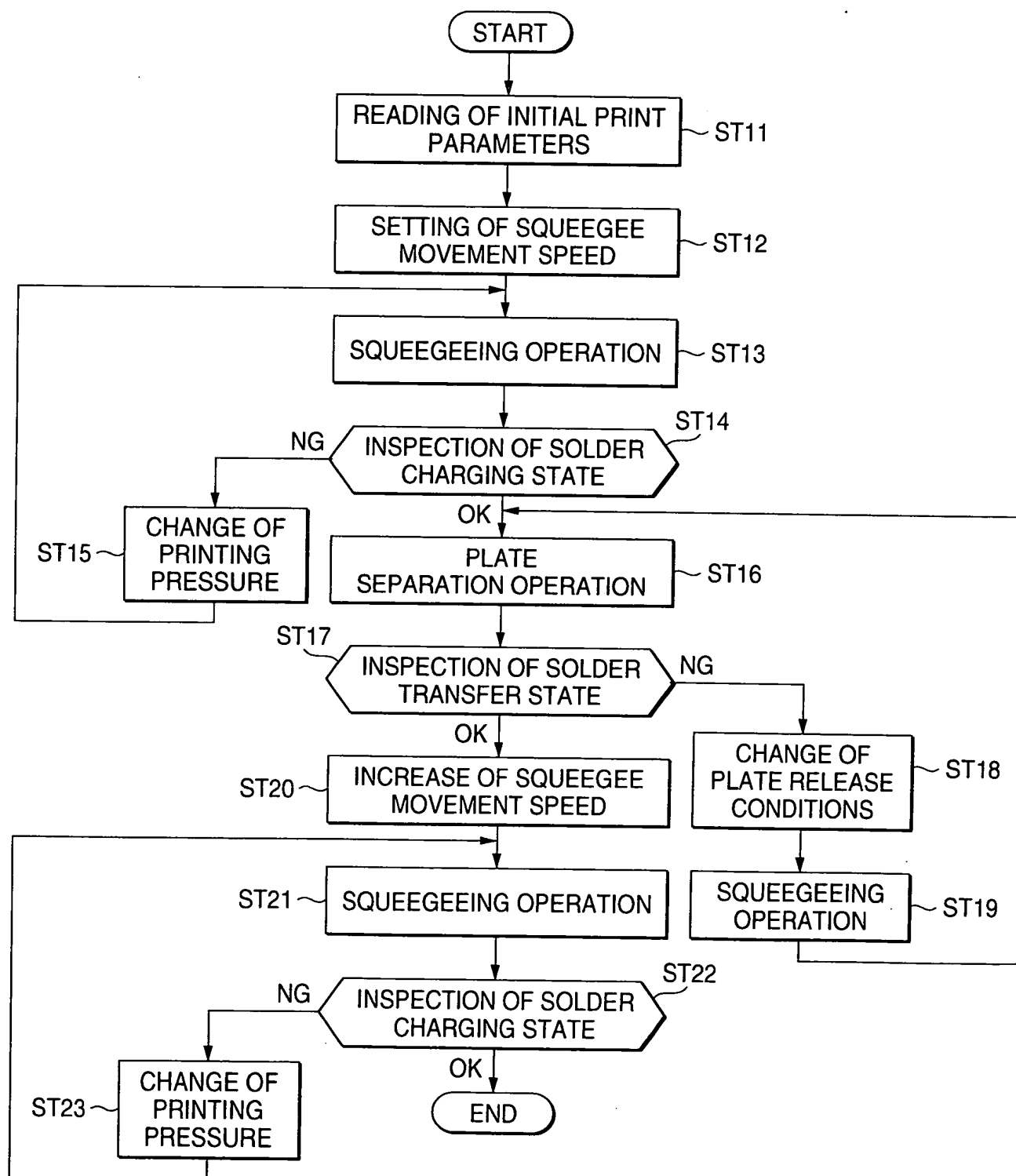


FIG. 13 (a)

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Parameter Setting Process (Semiautomatic)

Step 1

Squeegee Movement Speed

49




FIG. 13 (b)

40

Parameter Setting Process (Semiautomatic)

Squeegee Movement Speed

50

Step 2

Printing Pressure

51




FIG. 13 (c)

40

Parameter Setting Process (Semiautomatic)

Squeegee Movement Speed

50

Printing Pressure

52

Step 3

Plate Release Conditions

53a 53b 53

